DECLARATION AND POWER OF AFTORNEY

	entor, I hereby declare that:	
My residence, post off	ice and citizenship are as stated below next to my name,	
	inal, first and sole inventor (if only one name is listed below) or low) of the subject matter claimed and for which a pa N SYSTEM AND METHOD ON A FORWAR	
	[] was filed on as Application Serial amended on (if applicable	No. and was
I hereby state that I is amended by any amen	ave reviewed and understand the contents of the above identificant referred to above.	fied specification, including the claims, as
Code of Legelal KeEni	ł	
America, listeri below	priority benefits under 35 U.S.C. 119(a)-(d) or 365(b) of any for any PCT international application which designated at least cand have also identified below, by checking the box, any for international application having a filing date before that of the	the country other than the United States of
Prior Foreign Applica	tion(s):	Foreign Filing Date
Number	Country	Month/Day/Year
P2000-73665	KOREA	December 06, 2000
end end end end end end end end end end		
I hereby claim the bene Application Number	fft under 35 U.S.C.119(e) of any United States provisional application of the Provision of the Provi	ration(s) listed below.
A.D.		
I hereby claim the bene designating the United not disclosed in the pri 112, I acknowledge th	ifit under 35, U. S. C. 120 of any United States application(s), or States of America, listed below and, intofar as the subject matter or United States or PCT international application in the manner peduty to disclose information which is material to patentability ling date of the prior application and the national or PCT internations.	of each of the claims of this application is covided by the first paragraph of 35 U.S. C. as defined in 37 CFR 1.56 which became
I hereby claim the bene designating the United not disclosed in the pri 112, I acknowledge th	fit under 35, U. S. C. 120 of any United States application(s), or States of America, listed below and, insofar as the subject matter or United States or PCT international application in the manner peduty to disclose information which is material to patentability ling date of the prior application and the national or PCT internation	of each of the claims of this application is covided by the first paragraph of 35 U.S. C. as defined in 37 CFR 1.56 which became

I hereby appoint the following attorney(s) and/or agent(s); Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34, 196; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vasquez, Registration No. 38,647; Stuart I. Smith, Registration No. 42,159; Carol L. Druzbick, Registration No. 40,287; Anthony H.Nourse, Registration No. 46,121; and Margaret A. Burke, Registration No. 34,474, all of

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with full power of subs Office connected there	titution and revocation, to prosecute this application and to transact with, and all future correspondence should be addressed to them.	t all business in the Patent and Trademark
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